



#### **General Description**

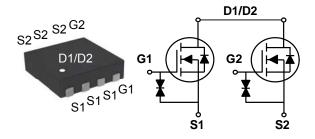
These N Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	$I_D$
20 V	8 mΩ	24 A

#### **Features**

- $R_{DS(ON)} \leq 8m\Omega@V_{GS} = 4.5V$
- · Fast switching
- · Green Device Available
- · Improved dv/dt capability

### DFN3x3 Dual Pin Configuration



## **Applications**

- · Handheld Instruments
- · POL Applications
- · Battery Protection Applications

Absolute Maximu	Absolute Maximum Ratings T <sub>c</sub> =25°C unless otherwise noted						
Symbol	Parameter	Rating	Units				
$V_{DS}$	Drain-Source Voltage	20	V				
$V_{GS}$	Gate-Source Voltage	±12	V				
1	Drain Current - Continuous (T <sub>C</sub> =25°C)	24	Α				
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> =100°C)	15	Α				
I <sub>DM</sub>	Drain Current - Pulsed (NOTE 1)	96	Α				
$P_D$	Power Dissipation (T <sub>C</sub> =25°C)	27	W				
' D	Power Dissipation - Derate above 25°C	0.22	W/°C				
$T_J$	Operating Junction Temperature Range	-50 to 150	°C				
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C				
Marking Code		NB8P0, EB2594P					

Thermal Characteristics					
Symbol	Parameter		Max.	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		62	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction to Case		4.55	°C/W	





# Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

### **Off Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , $I_D$ =250uA	20			V
I <sub>DSS</sub>	IDrain-Source Leakage Current	$V_{DS}$ =20V , $V_{GS}$ =0V , $T_J$ =25°C			1	uA
		$V_{DS}$ =16V , $V_{GS}$ =0V , $T_{J}$ =85 $^{\circ}$ C			10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ =±12V , $V_{DS}$ =0V			±20	uA

#### On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I Regions	Static Drain-Source On-Resistance (NOTE 3)	$V_{GS}$ =4.5V , $I_D$ =2.4A		6.7	8	
		$V_{GS}$ =4.0V , $I_D$ =2.4A		7.1	8.5	
		$V_{GS}$ =3.7V , $I_D$ =2.4A		7.3	9	mΩ
		$V_{GS}$ =3.1V , $I_D$ =2.4A		8	10.5	
		$V_{GS}$ =2.5V , $I_D$ =2.4A		9.2	12	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250uA$	0.5	0.65	1.5	V
gfs	Forward Transconductance	$V_{DS}$ =5V , $I_{D}$ =5A		15		S

### **Dynamic and switching Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
$Q_g$	Total Gate Charge	\\ -20\\ \\ -4.5\\   -5.0		13.8		
$Q_{gs}$	Gate-Source Charge	$V_{DS}$ =20V , $V_{GS}$ =4.5V , $I_{D}$ =5A (NOTE 2 \ 3)		2.1		nC
$Q_{gd}$	Gate-Drain Charge	(10122 3)		4.5		
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $I_{D}$ =5A , $R_{G}$ =6Ω (NOTE 2 \ 3)		28		
T <sub>r</sub>	Rise Time			64		nS
$T_{d(off)}$	Turn-Off Delay Time			60		113
T <sub>f</sub>	Fall Time			55		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , F=1MHz		1514		
C <sub>oss</sub>	Output Capacitance			178		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			145		

## **Drain-Source Diode Characteristics and Ratings**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			24	Α
I <sub>SM</sub>	Pulsed Source Current				48	Α
$V_{SD}$	Diode Forward Voltage	$V_{GS}$ =0V , $I_{S}$ =1A , $T_{J}$ =25 $^{\circ}$ C			1	V

## NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%.
- 3. Essentially independent of operating temperature.





### **Characteristics Curves**

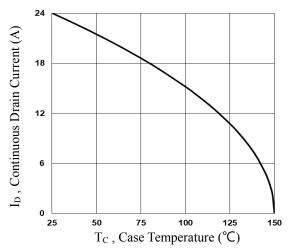


Fig.1 Continuous Drain Current vs. Tc

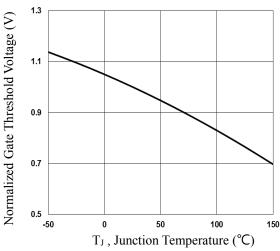


Fig.3 Normalized V<sub>th</sub> vs. T<sub>J</sub>

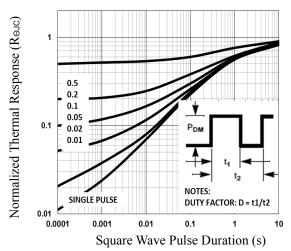


Fig.5 Normalized Transient Response

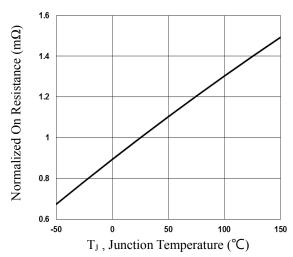


Fig.2 Normalized RDSON vs. TJ

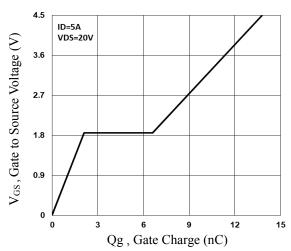


Fig.4 Gate Charge Waveform

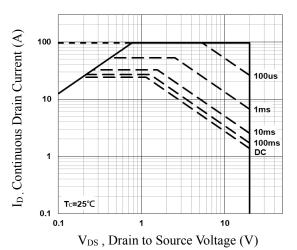


Fig.6 Maximum Safe Operation Area





### **Characteristics Curves**

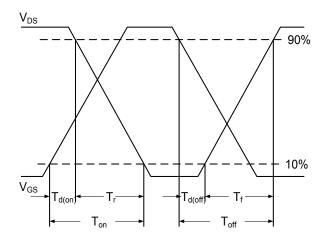


Fig.7 Switching Time Waveform

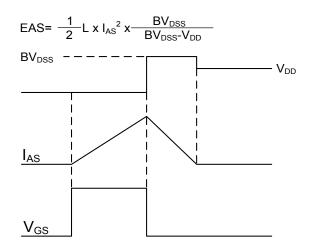
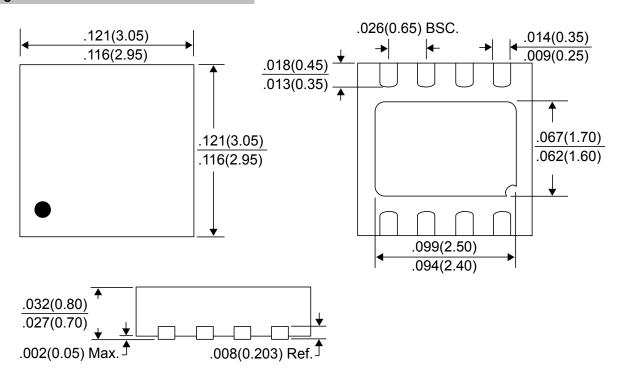


Fig.8 EAS Waveform

### **Package Outline Dimensions**



DFN3x3

Dimensions in inches and (millimeters)





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